

**Amendments to the Specification:**

Please replace paragraph [0005] with the following rewritten paragraph:

[0005] A thin film magnetic head assembly 10 includes element pads 2a; 2b and 3a; 3b which are exposed on the trailing surface 1A of the wafer 1. The element pads 2a and 2b are electrically connected to a MR element of the thin film magnetic head assembly 10 via leading wires 4a and 4b. The element pads 3a and 3b are electrically connected to a writing element 6 of the thin film magnetic head assembly 10 via leading wires 5a and 5b.